



MMST2222A

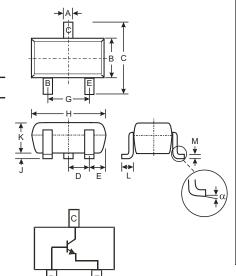
NPN SMALL SIGNAL SURFACE MOUNT TRANSISTOR

Features

- **Epitaxial Planar Die Construction**
- Complementary PNP Type Available (MMST2907A)
- Ultra-Small Surface Mount Package
- Lead Free/RoHS Compliant (Note 2)
- "Green" Device (Note 3 and 4)

Mechanical Data

- Case: SOT-323
- Case Material: Molded Plastic, "Green" Molding Compound, Note 4. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Terminal Connections: See Diagram
- Marking (See Page 2): K3P
- Ordering & Date Code Information: See Page 2
- Weight: 0.006 grams (approximate)



SOT-323							
Dim	Min	Max					
Α	0.25	0.40					
В	1.15	1.35					
С	2.00	2.20					
D	0.65 N	5 Nominal					
Е	0.30	0.40					
G	1.20	1.40					
Н	1.80	2.20					
J	0.0	0.10					
K	0.90	1.00					
L	0.25	0.40					
M	0.10	0.18					
α	0°	8°					
All Dimensions in mm							

Maximum Ratings @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	MMST2222A	Unit	
Collector-Base Voltage	V_{CBO}	75	V	
Collector-Emitter Voltage	V _{CEO}	40	V	
Emitter-Base Voltage	V _{EBO}	6.0	V	
Collector Current - Continuous (Note 1)	I _C	600	mA	
Power Dissipation (Note 1)	P _d	200	mW	
Thermal Resistance, Junction to Ambient (Note 1)	$R_{ heta JA}$	625	°C/W	
Operating and Storage and Temperature Range	T _j , T _{STG}	-55 to +150	°C	

1. Device mounted on FR-4 PCB, 1 inch x 0.85 inch x 0.062 inch; pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

- 2. No purposefully added lead.
- 3. Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com./products/lead_free/index.php.
- 4. Product manufactured with Date Code 0609 (week 9, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0609 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.



Electrical Characteristics @ T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Max	Unit	Test Condition		
OFF CHARACTERISTICS (Note 5)							
Collector-Base Breakdown Voltage	V _{(BR)CBO}	75	_	V	$I_C = 10 \mu A, I_E = 0$		
Collector-Emitter Breakdown Voltage	V _{(BR)CEO}	40	_	V	I _C = 10mA, I _B = 0		
Emitter-Base Breakdown Voltage	V _{(BR)EBO}	6.0	_	V	$I_E = 10\mu A, I_C = 0$		
Collector Cutoff Current	I _{CBO}	_	10	nA μA	V _{CB} = 60V, I _E = 0 V _{CB} = 60V, I _E = 0, T _A = 150°C		
Collector Cutoff Current	I _{CEX}	_	10	nA	V _{CE} = 60V, V _{EB(OFF)} = 3.0V		
Emitter Cutoff Current	I _{EBO}	_	10	nA	$V_{EB} = 3.0V, I_{C} = 0$		
Base Cutoff Current	I _{BL}	_	20	nA	$V_{CE} = 60V, V_{EB(OFF)} = 3.0V$		
ON CHARACTERISTICS (Note 5)							
DC Current Gain	h _{FE}	35 50 75 100 40 50 35	300	_	$\begin{array}{c} I_C = \ 100 \mu A, \ V_{CE} = \ 10V \\ I_C = \ 1.0 m A, \ V_{CE} = \ 10V \\ I_C = \ 10 m A, \ V_{CE} = \ 10V \\ I_C = \ 150 m A, \ V_{CE} = \ 10V \\ I_C = \ 500 m A, \ V_{CE} = \ 10V \\ I_C = \ 10 m A, \ V_{CE} = \ 10V, \ T_A = \ -55^{\circ}C \\ I_C = \ 150 m A, \ V_{CE} = \ 1.0V \end{array}$		
Collector-Emitter Saturation Voltage	V _{CE(SAT)}	_	0.3 1.0	V	I _C = 150mA, I _B = 15mA I _C = 500mA, I _B = 50mA		
Base-Emitter Saturation Voltage	V _{BE(SAT)}	0.6	1.2 2.0	V	I _C = 150mA, I _B = 15mA I _C = 500mA, I _B = 50mA		
SMALL SIGNAL CHARACTERISTICS			•	•			
Output Capacitance	C _{obo}	_	8	pF	$V_{CB} = 10V$, $f = 1.0MHz$, $I_E = 0$		
Input Capacitance	C _{ibo}	_	25	pF	V _{EB} = 0.5V, f = 1.0MHz, I _C = 0		
Current Gain-Bandwidth Product	f⊤	300	_	MHz	V _{CE} = 20V, I _C = 20mA, f = 100MHz		
Noise Figure	NF	_	4.0	dB	$V_{CE} = 10V, I_{C} = 100\mu A, R_{S} = 1.0k\Omega, f = 1.0kHz$		
SWITCHING CHARACTERISTICS							
Delay Time	t _d	_	10	ns	V _{CC} = 30V, I _C = 150mA,		
Rise Time	t _r	_	25	ns	$V_{BE(off)} = -0.5V, I_{B1} = 15mA$		
Storage Time	ts	_	225	ns	V _{CC} = 30V, I _C = 150mA,		
Fall Time	t _f	_	60	ns	$I_{B1} = I_{B2} = 15\text{mA}$		

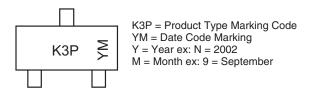
Ordering Information (Note 4 & 6)

Device	Packaging	Shipping			
MMST2222A-7-F	SOT-323	3000/Tape & Reel			

Notes: 4. Product manufactured with Date Code 0609 (week 9, 2006) and newer are built with Green Molding Compound. Product manufactured prior to Date Code 0609 are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

- 5. Short duration test pulse used to minimize self-heating effect.
- 6. For Packaging Details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

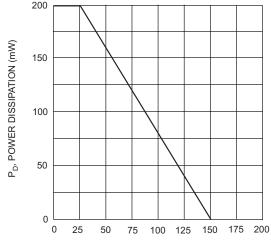
Marking Information



Date Code Key

Year	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009
Code	J	K	L	М	N	Р	R	S	Т	U	V	W
Month	Jan	Feb	March	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D





T_A, AMBIENT TEMPERATURE (°C) Fig. 1, Max Power Dissipation vs Ambient Temperature

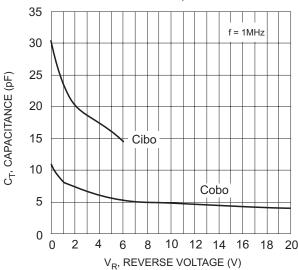


Fig. 3, Typical Capacitance Characteristics

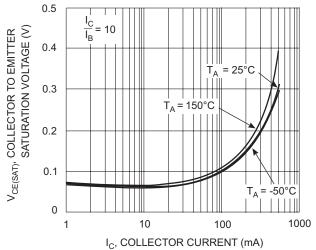
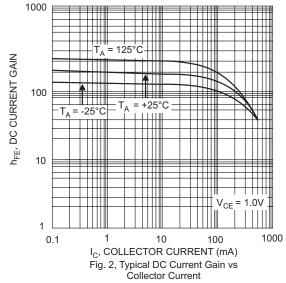


Fig. 5, Collector-Emitter Saturation Voltage vs. Collector Current



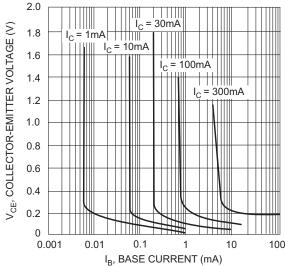


Fig. 4, Typical Collector Saturation Region

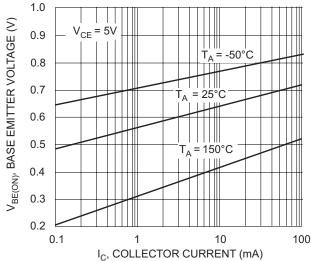
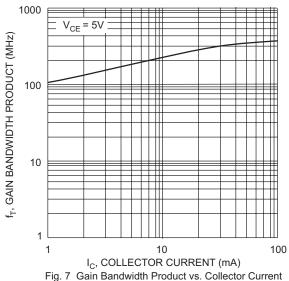


Fig. 6, Base-Emitter Voltage vs. Collector Current





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